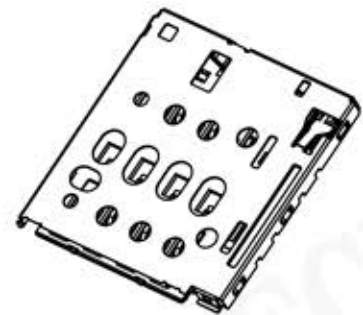
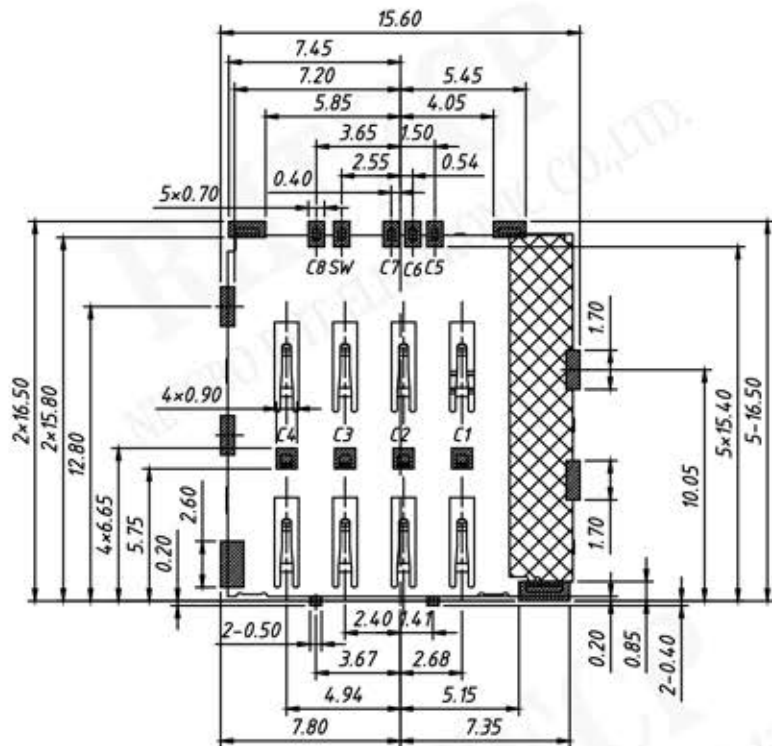


Micro SIM Card



3D REFERENCE MODE F

UNITS:mm	SHEET SIZE:A4		SCALE: ---
> 0~3	> 3~18	> 18~50	> 50~120
± 0.12	± 0.15	± 0.3	± 0.5



■ CIRCUT TRACE KEEP OUT AREA  
 ▨ SMT SOLDER AREA

RECOMMENDED PCB LAYOUT  
 COMPONENT SIDE(TOLERANCE ±0.05)

SIM Pin Assignment	
Pin No.	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

**Material:**

.Housing:High Temperature Thermoplastic,UL94V-0  
 .Contact:Copper Alloy,Au 1u",Solder area:Gold Flash;Under plate Ni 40u"  
 Min all over  
 .Shell:SUS,Plated 30U" Ni Overall,Solder area:Gold Flash

**Electrical:**

Current Rating: 0.5A  
 Voltage Rating:50V DC Max.  
 Contact Resistance:100mΩ Max.  
 Dielectric Withstanding Voltage:500V AC  
 Insulation Resistance:1000MΩ Min./250VDC  
 Ambient Temperature Range:-20° C ~ +85° C  
 Storage Temperature Range:-40° C ~ +70° C  
 Ambient Humidity Range:95% R.H. Max.  
 Peak Temperature:260° ±5° C  
 Mating Cycles:5000 Insertions

CARD INSERTION STATE	CARD DETECT SW
CARD UN-INSERTION	CLOSE  SW CONTACT B (CARD DETECTION SIGNAL) SW CONTACT A (USE ONLE)
CARD INSERTION	OPEN  SW CONTACT B (CARD DETECTION SIGNAL) SW CONTACT A (USE ONLE)